

LM158/LM258/LM358/LM2904 Low Power Dual Operational Amplifiers

Check for Samples: [LM158-N](#), [LM258-N](#), [LM2904-N](#), [LM358-N](#)

FEATURES

- Available in 8-Bump micro SMD chip sized package, (See AN-1112)
- Internally frequency compensated for unity gain
- Large dc voltage gain: 100 dB
- Wide bandwidth (unity gain): 1 MHz (temperature compensated)
- Wide power supply range:
 - Single supply: 3V to 32V
 - or dual supplies: $\pm 1.5\text{V}$ to $\pm 16\text{V}$
- Very low supply current drain (500 μA)—essentially independent of supply voltage
- Low input offset voltage: 2 mV
- Input common-mode voltage range includes ground
- Differential input voltage range equal to the power supply voltage
- Large output voltage swing

UNIQUE CHARACTERISTICS

- In the linear mode the input common-mode voltage range includes ground and the output voltage can also swing to ground, even though operated from only a single power supply voltage.
- The unity gain cross frequency is temperature compensated.
- The input bias current is also temperature compensated.

ADVANTAGES

- Two internally compensated op amps
- Eliminates need for dual supplies
- Allows direct sensing near GND and V_{OUT} also goes to GND
- Compatible with all forms of logic
- Power drain suitable for battery operation

DESCRIPTION

The LM158 series consists of two independent, high gain, internally frequency compensated operational amplifiers which were designed specifically to operate from a single power supply over a wide range of voltages. Operation from split power supplies is also possible and the low power supply current drain is independent of the magnitude of the power supply voltage.

Application areas include transducer amplifiers, dc gain blocks and all the conventional op amp circuits which now can be more easily implemented in single power supply systems. For example, the LM158 series can be directly operated off of the standard +5V power supply voltage which is used in digital systems and will easily provide the required interface electronics without requiring the additional $\pm 15\text{V}$ power supplies.

The LM358 and LM2904 are available in a chip sized package (8-Bump micro SMD) using National's micro SMD package technology.

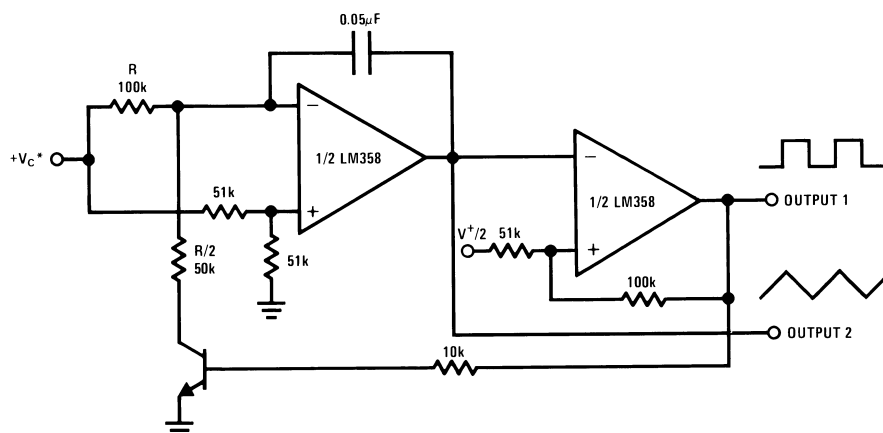


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VOLTAGE CONTROLLED OSCILLATOR (VCO)

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾

	LM158/LM258/LM358	LM2904
	LM158A/LM258A/LM358A	
Supply Voltage, V^+	32V	26V
Differential Input Voltage	32V	26V
Input Voltage	-0.3V to +32V	-0.3V to +26V
Power Dissipation ⁽²⁾		
Molded DIP	830 mW	830 mW
Metal Can	550 mW	
Small Outline Package (M)	530 mW	530 mW
micro SMD	435mW	
Output Short-Circuit to GND		
(One Amplifier) ⁽³⁾		
$V^+ \leq 15V$ and $T_A = 25^\circ C$	Continuous	Continuous
Input Current ($V_{IN} < -0.3V$) ⁽⁴⁾	50 mA	50 mA
Operating Temperature Range		
LM358	0°C to +70°C	-40°C to +85°C
LM258	-25°C to +85°C	
LM158	-55°C to +125°C	
Storage Temperature Range	-65°C to +150°C	-65°C to +150°C
Lead Temperature, DIP		
(Soldering, 10 seconds)	260°C	260°C
Lead Temperature, Metal Can		
(Soldering, 10 seconds)	300°C	300°C
Soldering Information		
Dual-In-Line Package		
Soldering (10 seconds)	260°C	260°C
Small Outline Package		
Vapor Phase (60 seconds)	215°C	215°C
Infrared (15 seconds)	220°C	220°C
See AN-450 "Surface Mounting Methods and Their Effect on Product Reliability" for other methods of soldering surface mount devices.		
ESD Tolerance ⁽⁵⁾	250V	250V

- (1) Refer to RETS158AX for LM158A military specifications and to RETS158X for LM158 military specifications.
- (2) For operating at high temperatures, the LM358/LM358A, LM2904 must be derated based on a +125°C maximum junction temperature and a thermal resistance of 120°C/W for MDIP, 182°C/W for Metal Can, 189°C/W for Small Outline package, and 230°C/W for micro SMD, which applies for the device soldered in a printed circuit board, operating in a still air ambient. The LM258/LM258A and LM158/LM158A can be derated based on a +150°C maximum junction temperature. The dissipation is the total of both amplifiers—use external resistors, where possible, to allow the amplifier to saturate or to reduce the power which is dissipated in the integrated circuit.
- (3) Short circuits from the output to V^+ can cause excessive heating and eventual destruction. When considering short circuits to ground, the maximum output current is approximately 40 mA independent of the magnitude of V^+ . At values of supply voltage in excess of +15V, continuous short-circuits can exceed the power dissipation ratings and cause eventual destruction. Destructive dissipation can result from simultaneous shorts on all amplifiers.
- (4) This input current will only exist when the voltage at any of the input leads is driven negative. It is due to the collector-base junction of the input PNP transistors becoming forward biased and thereby acting as input diode clamps. In addition to this diode action, there is also lateral NPN parasitic transistor action on the IC chip. This transistor action can cause the output voltages of the op amps to go to the V^+ voltage level (or to ground for a large overdrive) for the time duration that an input is driven negative. This is not destructive and normal output states will re-establish when the input voltage, which was negative, again returns to a value greater than -0.3V (at 25°C).
- (5) Human body model, 1.5 k Ω in series with 100 pF.

Electrical Characteristics

$V^+ = +5.0V$, unless otherwise stated

Parameter	Conditions	LM158A			LM358A			LM158/LM258			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage	⁽¹⁾ , $T_A = 25^\circ C$		1	2		2	3		2	5	mV
Input Bias Current	$I_{IN(+)}$ or $I_{IN(-)}$, $T_A = 25^\circ C$, $V_{CM} = 0V$, ⁽²⁾		20	50		45	100		45	150	nA
Input Offset Current	$I_{IN(+)} - I_{IN(-)}$, $V_{CM} = 0V$, $T_A = 25^\circ C$		2	10		5	30		3	30	nA
Input Common-Mode Voltage Range	$V^+ = 30V$, ⁽³⁾	0		$V^+ - 1.5$	0		$V^+ - 1.5$	0		$V^+ - 1.5$	V
Supply Current	Over Full Temperature Range										
	$R_L = \infty$ on All Op Amps										
	$V^+ = 30V$ (LM2904 $V^+ = 26V$)		1	2		1	2		1	2	mA
	$V^+ = 5V$		0.5	1.2		0.5	1.2		0.5	1.2	mA

- $V_O \approx 1.4V$, $R_S = 0\Omega$ with V^+ from 5V to 30V; and over the full input common-mode range (0V to $V^+ - 1.5V$) at $25^\circ C$. For LM2904, V^+ from 5V to 26V.
- The direction of the input current is out of the IC due to the PNP input stage. This current is essentially constant, independent of the state of the output so no loading change exists on the input lines.
- The input common-mode voltage of either input signal voltage should not be allowed to go negative by more than 0.3V (at $25^\circ C$). The upper end of the common-mode voltage range is $V^+ - 1.5V$ (at $25^\circ C$), but either or both inputs can go to +32V without damage (+26V for LM2904), independent of the magnitude of V^+ .

Electrical Characteristics

$V^+ = +5.0V$, unless otherwise stated

Parameter	Conditions	LM358			LM2904			Units
		Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage	⁽¹⁾ , $T_A = 25^\circ C$		2	7		2	7	mV
Input Bias Current	$I_{IN(+)}$ or $I_{IN(-)}$, $T_A = 25^\circ C$, $V_{CM} = 0V$, ⁽²⁾		45	250		45	250	nA
Input Offset Current	$I_{IN(+)} - I_{IN(-)}$, $V_{CM} = 0V$, $T_A = 25^\circ C$		5	50		5	50	nA
Input Common-Mode Voltage Range	$V^+ = 30V$, ⁽³⁾ (LM2904, $V^+ = 26V$), $T_A = 25^\circ C$	0		$V^+ - 1.5$	0		$V^+ - 1.5$	V
Supply Current	Over Full Temperature Range							
	$R_L = \infty$ on All Op Amps							
	$V^+ = 30V$ (LM2904 $V^+ = 26V$)		1	2		1	2	mA
	$V^+ = 5V$		0.5	1.2		0.5	1.2	mA

- $V_O \approx 1.4V$, $R_S = 0\Omega$ with V^+ from 5V to 30V; and over the full input common-mode range (0V to $V^+ - 1.5V$) at $25^\circ C$. For LM2904, V^+ from 5V to 26V.
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Electrical Characteristics

$V^+ = +5.0V$, ⁽¹⁾, unless otherwise stated

Parameter	Conditions	LM158A			LM358A			LM158/LM258			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Large Signal Voltage Gain	$V^+ = 15V$, $T_A = 25^\circ C$, $R_L \geq 2 k\Omega$, (For $V_O = 1V$ to $11V$)	50	100		25	100		50	100		V/mV

- These specifications are limited to $-55^\circ C \leq T_A \leq +125^\circ C$ for the LM158/LM158A. With the LM258/LM258A, all temperature specifications are limited to $-25^\circ C \leq T_A \leq +85^\circ C$, the LM358/LM358A temperature specifications are limited to $0^\circ C \leq T_A \leq +70^\circ C$, and the LM2904 specifications are limited to $-40^\circ C \leq T_A \leq +85^\circ C$.

Electrical Characteristics (continued)

 $V^+ = +5.0V$, ⁽¹⁾, unless otherwise stated

Parameter		Conditions		LM158A			LM358A			LM158/LM258			Units		
				Min	Typ	Max	Min	Typ	Max	Min	Typ	Max			
Common-Mode		T _A = 25°C,		70	85		65	85		70	85		dB		
Rejection Ratio		V _{CM} = 0V to V ⁺ –1.5V													
Power Supply		V ⁺ = 5V to 30V		65	100		65	100		65	100		dB		
Rejection Ratio		(LM2904, V ⁺ = 5V to 26V), T _A = 25°C													
Amplifier-to-Amplifier Coupling		f = 1 kHz to 20 kHz, T _A = 25°C (Input Referred), ⁽²⁾			–120			–120			–120		dB		
Output Current	Source	V _{IN} ⁺ = 1V,		20	40		20	40		20	40		mA		
		V _{IN} [–] = 0V,													
		V ⁺ = 15V,													
		V _O = 2V, T _A = 25°C													
	Sink	V _{IN} [–] = 1V, V _{IN} ⁺ = 0V											mA		
		V ⁺ = 15V, T _A = 25°C,		10	20			10		20				10	20
		V _O = 2V													
		V _{IN} [–] = 1V,		12	50		12	50		12	50		μA		
		V _{IN} ⁺ = 0V													
		T _A = 25°C, V _O = 200 mV,													
V ⁺ = 15V															
Short Circuit to Ground		T _A = 25°C, ⁽³⁾ , V ⁺ = 15V			40	60		40	60		40	60	mA		
Input Offset Voltage		⁽⁴⁾				4		5			7	mV			
Input Offset Voltage Drift		R _S = 0Ω			7	15		7	20		7		μV/°C		
Input Offset Current		I _{IN(+)} – I _{IN(–)}				30		75			100	nA			
Input Offset Current Drift		R _S = 0Ω			10	200		10	300		10		pA/°C		
Input Bias Current		I _{IN(+)} or I _{IN(–)}			40	100		40	200		40	300	nA		
Input Common-Mode Voltage Range		V ⁺ = 30 V, ⁽⁵⁾ (LM2904, V ⁺ = 26V)		0		V ⁺ –2	0		V ⁺ –2	0		V ⁺ –2	V		
Large Signal Voltage Gain		V ⁺ = +15V		25			15			25			V/mV		
		(V _O = 1V to 11V)													
		R _L ≥ 2 kΩ													
Output	V _{OH}	V ⁺ = +30V	R _L = 2 kΩ	26			26			26			V		
Voltage		(LM2904, V ⁺ = 26V)	R _L = 10 kΩ	27	28		27	28		27	28		V		
Swing	V _{OL}	V ⁺ = 5V, R _L = 10 kΩ			5	20		5	20		5	20	mV		
Output Current	Source	V _{IN} ⁺ = +1V, V _{IN} [–] = 0V,		10	20		10	20		10	20		mA		
		V ⁺ = 15V, V _O = 2V													
	Sink	V _{IN} [–] = +1V, V _{IN} ⁺ = 0V,		10	15		5	8		5	8		mA		
		V ⁺ = 15V, V _O = 2V													

- (2) Due to proximity of external components, insure that coupling is not originating via stray capacitance between these external parts. This typically can be detected as this type of capacitance increases at higher frequencies.
- (3) Short circuits from the output to V^+ can cause excessive heating and eventual destruction. When considering short circuits to ground, the maximum output current is approximately 40 mA independent of the magnitude of V^+ . At values of supply voltage in excess of +15V, continuous short-circuits can exceed the power dissipation ratings and cause eventual destruction. Destructive dissipation can result from simultaneous shorts on all amplifiers.
- (4) $V_O \approx 1.4V$, $R_S = 0\Omega$ with V^+ from 5V to 30V; and over the full input common-mode range (0V to $V^+ - 1.5V$) at $25^\circ C$. For LM2904, V^+ from 5V to 26V.
- (5) The input common-mode voltage of either input signal voltage should not be allowed to go negative by more than 0.3V (at $25^\circ C$). The upper end of the common-mode voltage range is $V^+ - 1.5V$ (at $25^\circ C$), but either or both inputs can go to +32V without damage (+26V for LM2904), independent of the magnitude of V^+ .

Electrical Characteristics

$V^+ = +5.0V$, ⁽¹⁾, unless otherwise stated

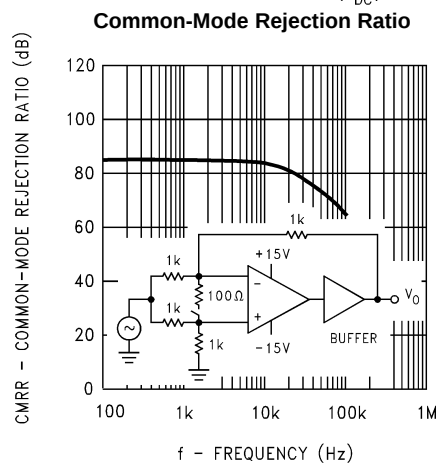
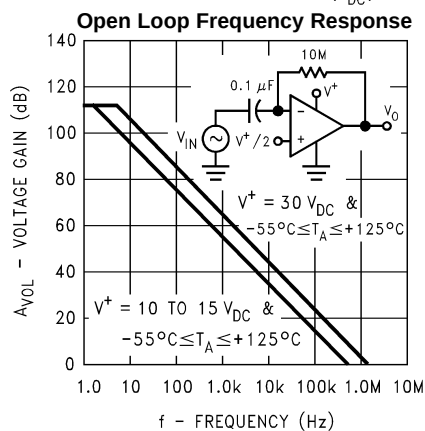
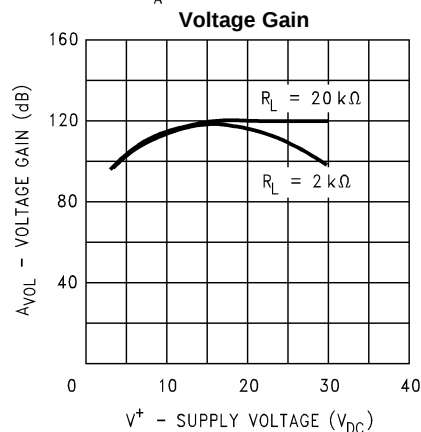
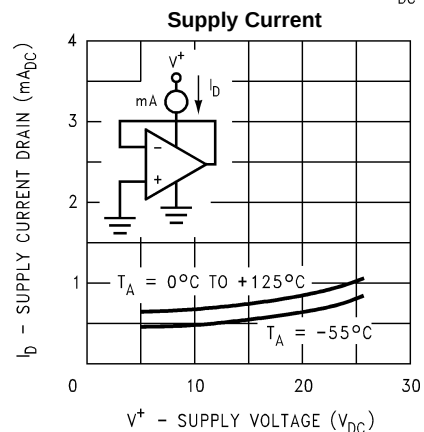
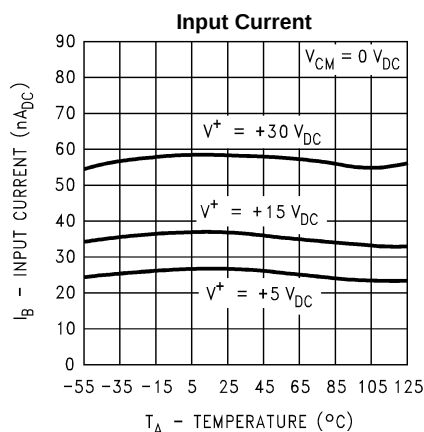
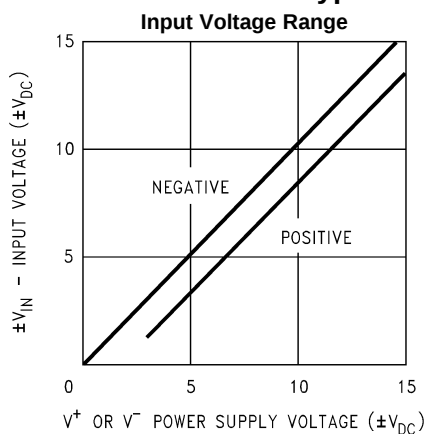
Parameter		Conditions		LM358			LM2904			Units
				Min	Typ	Max	Min	Typ	Max	
Large Signal Voltage		V ⁺ = 15V, T _A = 25°C,								
Gain		R _L ≥ 2 kΩ, (For V _O = 1V to 11V)		25	100		25	100	V/mV	
Common-Mode Rejection Ratio		T _A = 25°C,		65	85		50	70	dB	
		V _{CM} = 0V to V ⁺ –1.5V								
Power Supply Rejection Ratio		V ⁺ = 5V to 30V		65	100		50	100	dB	
		(LM2904, V ⁺ = 5V to 26V), T _A = 25°C								
Amplifier-to-Amplifier Coupling		f = 1 kHz to 20 kHz, T _A = 25°C (Input Referred), ⁽²⁾			–120			–120	dB	
Output Current	Source	V _{IN} ⁺ = 1V,		20	40		20	40	mA	
		V _{IN} [–] = 0V,								
		V ⁺ = 15V,								
		V _O = 2V, T _A = 25°C								
	Sink	V _{IN} [–] = 1V, V _{IN} ⁺ = 0V		10	20		10	20	mA	
		V ⁺ = 15V, T _A = 25°C,								
		V _O = 2V								
			V _{IN} [–] = 1V,		12	50		12	50	μA
			V _{IN} ⁺ = 0V							
			T _A = 25°C, V _O = 200 mV,							
V ⁺ = 15V										
Short Circuit to Ground		T _A = 25°C, ⁽³⁾ , V ⁺ = 15V			40	60		40	60	mA
Input Offset Voltage		⁽⁴⁾				9			10	mV
Input Offset Voltage Drift		R _S = 0Ω			7			7		μV/°C
Input Offset Current		I _{IN(+)} – I _{IN(–)}				150		45	200	nA
Input Offset Current Drift		R _S = 0Ω			10			10		pA/°C
Input Bias Current		I _{IN(+)} or I _{IN(–)}			40	500		40	500	nA
Input Common-Mode Voltage Range		V ⁺ = 30 V, ⁽⁵⁾ (LM2904, V ⁺ = 26V)		0		V ⁺ –2	0		V ⁺ –2	V
Large Signal Voltage Gain		V ⁺ = +15V		15			15			V/mV
		(V _O = 1V to 11V)								
		R _L ≥ 2 kΩ								
Output	V _{OH}	V ⁺ = +30V	R _L = 2 kΩ	26			22			V
Voltage		(LM2904, V ⁺ = 26V)	R _L = 10 kΩ	27	28		23	24		V
Swing	V _{OL}	V ⁺ = 5V, R _L = 10 kΩ			5	20		5	100	mV

- (1) These specifications are limited to $-55^\circ C \leq T_A \leq +125^\circ C$ for the LM158/LM158A. With the LM258/LM258A, all temperature specifications are limited to $-25^\circ C \leq T_A \leq +85^\circ C$, the LM358/LM358A temperature specifications are limited to $0^\circ C \leq T_A \leq +70^\circ C$, and the LM2904 specifications are limited to $-40^\circ C \leq T_A \leq +85^\circ C$.
- (2) Due to proximity of external components, insure that coupling is not originating via stray capacitance between these external parts. This typically can be detected as this type of capacitance increases at higher frequencies.
- (3) Short circuits from the output to V^+ can cause excessive heating and eventual destruction. When considering short circuits to ground, the maximum output current is approximately 40 mA independent of the magnitude of V^+ . At values of supply voltage in excess of +15V, continuous short-circuits can exceed the power dissipation ratings and cause eventual destruction. Destructive dissipation can result from simultaneous shorts on all amplifiers.
- (4) $V_O = 1.4V$, $R_S = 0\Omega$ with V^+ from 5V to 30V; and over the full input common-mode range (0V to $V^+ - 1.5V$) at $25^\circ C$. For LM2904, V^+ from 5V to 26V.
- (5) The input common-mode voltage of either input signal voltage should not be allowed to go negative by more than 0.3V (at $25^\circ C$). The upper end of the common-mode voltage range is $V^+ - 1.5V$ (at $25^\circ C$), but either or both inputs can go to +32V without damage (+26V for LM2904), independent of the magnitude of V^+ .

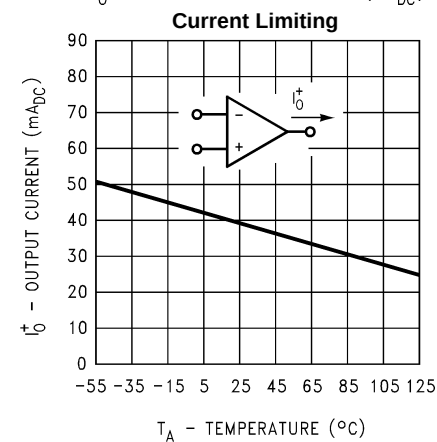
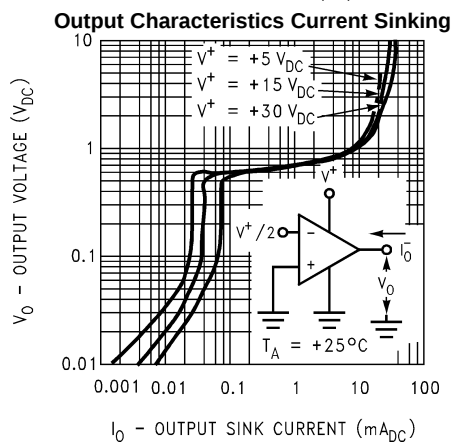
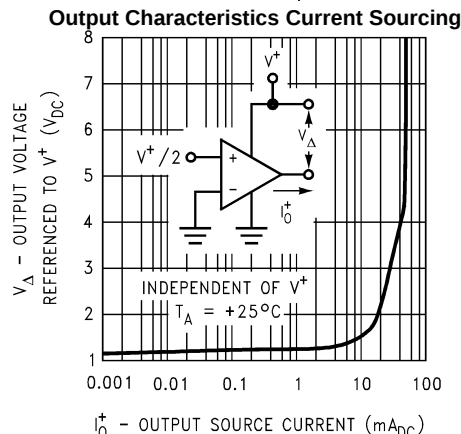
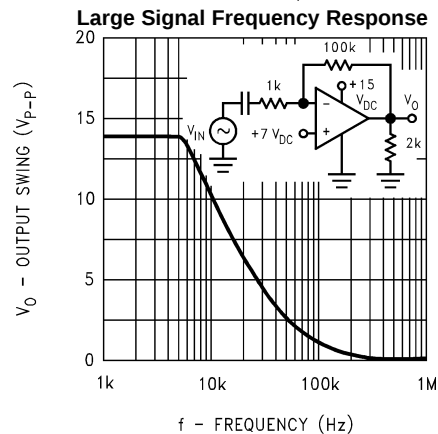
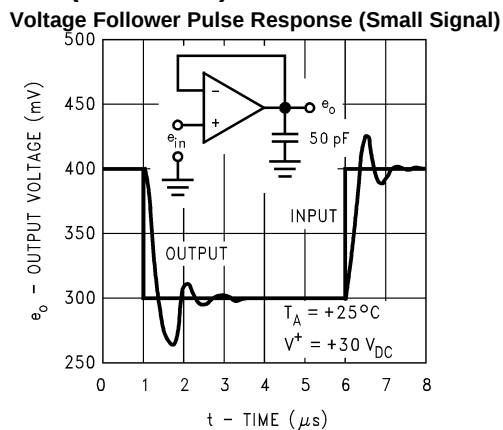
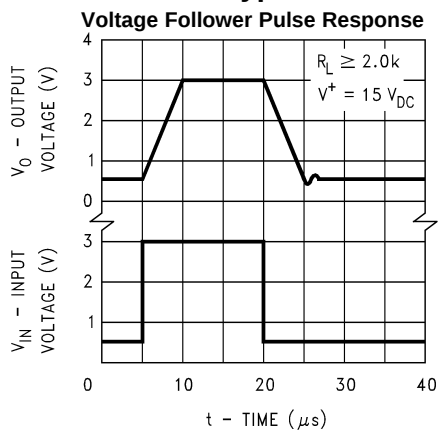
Electrical Characteristics (continued)
 $V^+ = +5.0V$, ⁽¹⁾, unless otherwise stated

Parameter		Conditions	LM358			LM2904			Units
			Min	Typ	Max	Min	Typ	Max	
Output Current	Source	$V_{IN}^+ = +1V$, $V_{IN}^- = 0V$,	10	20		10	20		mA
		$V^+ = 15V$, $V_O = 2V$							
	Sink	$V_{IN}^- = +1V$, $V_{IN}^+ = 0V$,	5	8		5	8		mA
		$V^+ = 15V$, $V_O = 2V$							

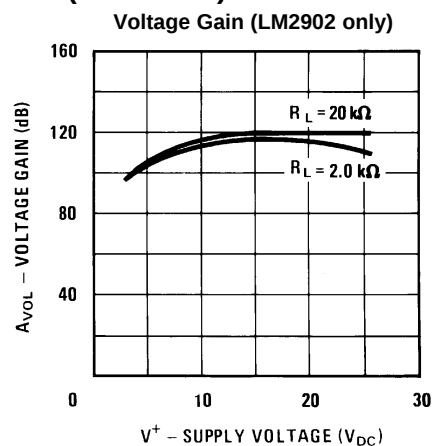
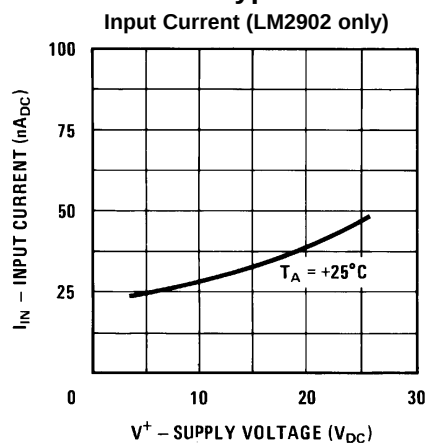
Typical Performance Characteristics



Typical Performance Characteristics (continued)



Typical Performance Characteristics (continued)



APPLICATION HINTS

The LM158 series are op amps which operate with only a single power supply voltage, have true-differential inputs, and remain in the linear mode with an input common-mode voltage of 0 V_{DC}. These amplifiers operate over a wide range of power supply voltage with little change in performance characteristics. At 25°C amplifier operation is possible down to a minimum supply voltage of 2.3 V_{DC}.

Precautions should be taken to insure that the power supply for the integrated circuit never becomes reversed in polarity or that the unit is not inadvertently installed backwards in a test socket as an unlimited current surge through the resulting forward diode within the IC could cause fusing of the internal conductors and result in a destroyed unit.

Large differential input voltages can be easily accommodated and, as input differential voltage protection diodes are not needed, no large input currents result from large differential input voltages. The differential input voltage may be larger than V⁺ without damaging the device. Protection should be provided to prevent the input voltages from going negative more than -0.3 V_{DC} (at 25°C). An input clamp diode with a resistor to the IC input terminal can be used.

To reduce the power supply current drain, the amplifiers have a class A output stage for small signal levels which converts to class B in a large signal mode. This allows the amplifiers to both source and sink large output currents. Therefore both NPN and PNP external current boost transistors can be used to extend the power capability of the basic amplifiers. The output voltage needs to raise approximately 1 diode drop above ground to bias the on-chip vertical PNP transistor for output current sinking applications.

For ac applications, where the load is capacitively coupled to the output of the amplifier, a resistor should be used, from the output of the amplifier to ground to increase the class A bias current and prevent crossover distortion. Where the load is directly coupled, as in dc applications, there is no crossover distortion.

Capacitive loads which are applied directly to the output of the amplifier reduce the loop stability margin. Values of 50 pF can be accommodated using the worst-case non-inverting unity gain connection. Large closed loop gains or resistive isolation should be used if larger load capacitance must be driven by the amplifier.

The bias network of the LM158 establishes a drain current which is independent of the magnitude of the power supply voltage over the range of 3 V_{DC} to 30 V_{DC}.

Output short circuits either to ground or to the positive power supply should be of short time duration. Units can be destroyed, not as a result of the short circuit current causing metal fusing, but rather due to the large increase in IC chip dissipation which will cause eventual failure due to excessive junction temperatures. Putting direct short-circuits on more than one amplifier at a time will increase the total IC power dissipation to destructive levels, if not properly protected with external dissipation limiting resistors in series with the output leads of the amplifiers. The larger value of output source current which is available at 25°C provides a larger output current capability at elevated temperatures (see [Typical Performance Characteristics](#)) than a standard IC op amp.

The circuits presented in the [Typical Single-Supply Applications](#) emphasize operation on only a single power supply voltage. If complementary power supplies are available, all of the standard op amp circuits can be used. In general, introducing a pseudo-ground (a bias voltage reference of V⁺/2) will allow operation above and below this value in single power supply systems. Many application circuits are shown which take advantage of the wide input common-mode voltage range which includes ground. In most cases, input biasing is not required and input voltages which range to ground can easily be accommodated.

CONNECTION DIAGRAM

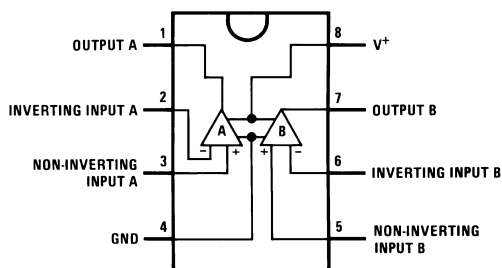


Figure 1. Top View - DIP/SO Package

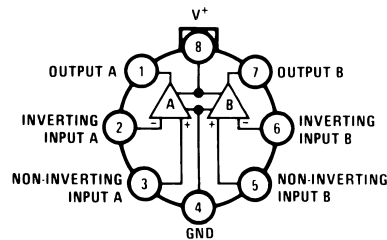


Figure 2. Top View - Metal Can Package

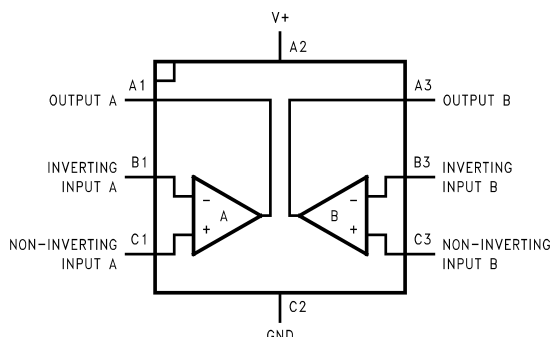


Figure 3. 8-Bump micro SMD - Top View (Bump Side Down)

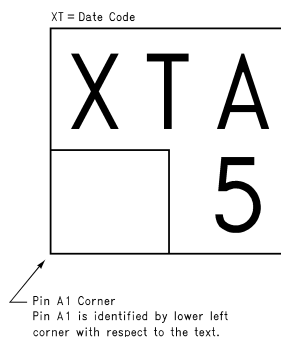


Figure 4. Top View - LM358BP micro SMD Marking Orientation

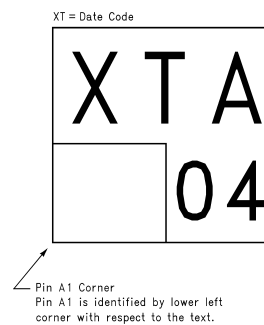


Figure 5. Top View - LM2904BP micro SMD Marking Orientation

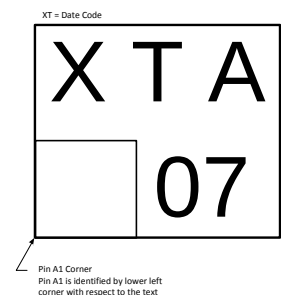


Figure 6. Top View - LM358TP micro SMD Marking Orientation

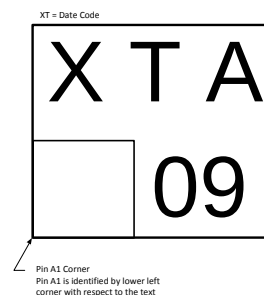
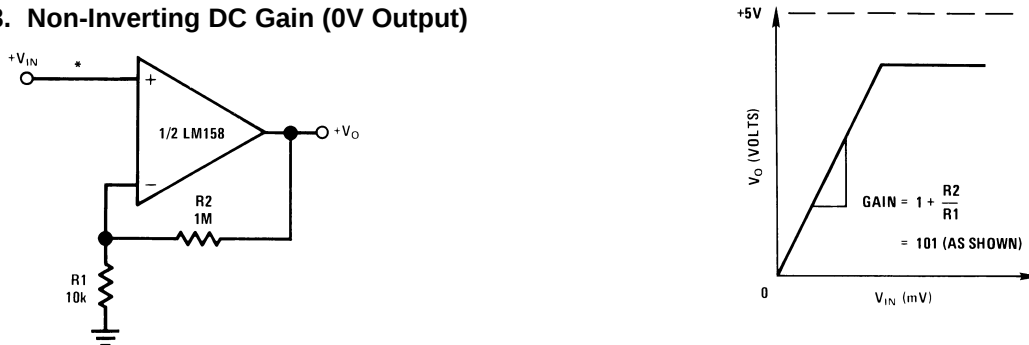


Figure 7. Top View - LM2904ITP micro SMD Marking Orientation

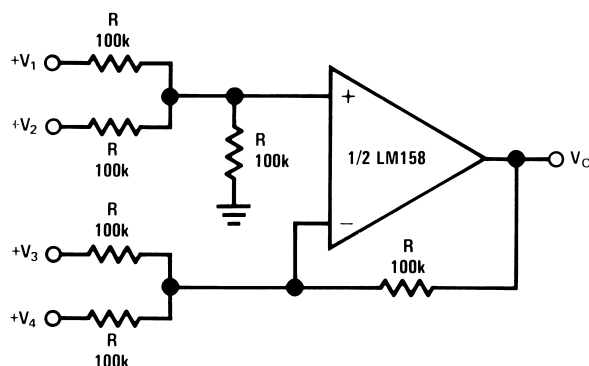
TYPICAL SINGLE-SUPPLY APPLICATIONS

($V^+ = 5.0 V_{DC}$)

Figure 8. Non-Inverting DC Gain (0V Output)

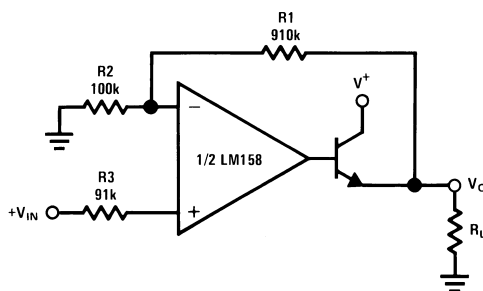


*R not needed due to temperature independent I_{IN}



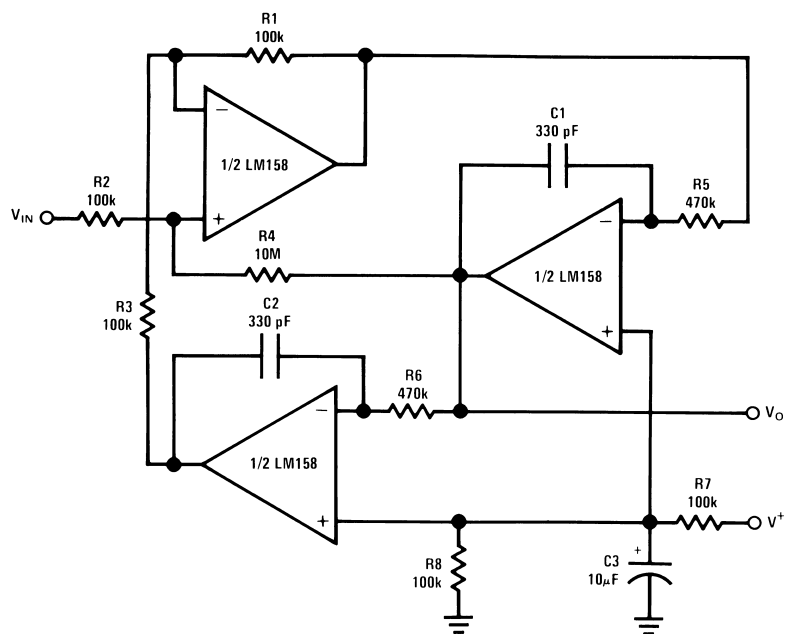
Where: $V_O = V_1 + V_2 - V_3 - V_4$
 $(V_1 + V_2) \geq (V_3 + V_4)$ to keep $V_O > 0 V_{DC}$

Figure 9. DC Summing Amplifier
 $(V_{IN}'S \geq 0 V_{DC} \text{ and } V_O \geq 0 V_{DC})$



$V_O = 0 V_{DC}$ for $V_{IN} = 0 V_{DC}$
 $A_V = 10$

Figure 10. Power Amplifier



$f_0 = 1 \text{ kHz}$
 $Q = 50$
 $A_v = 100 \text{ (40 dB)}$

Figure 11. "BI-QUAD" RC Active Bandpass Filter

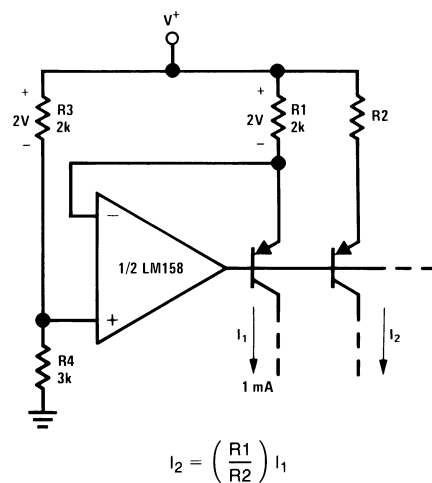


Figure 12. Fixed Current Sources

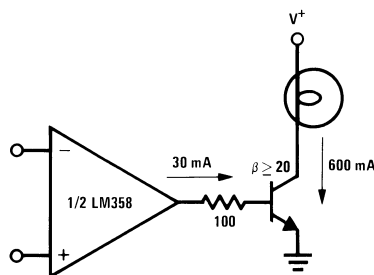


Figure 13. Lamp Driver

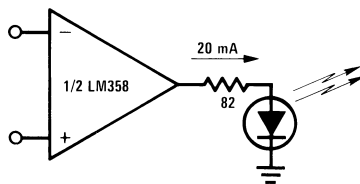
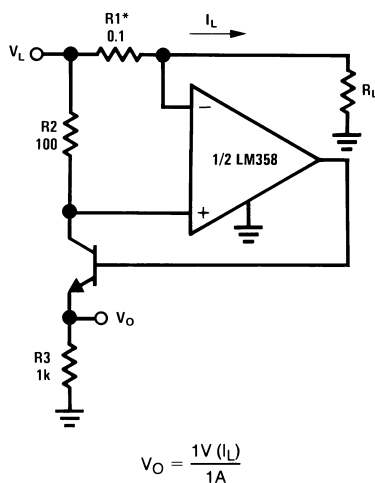


Figure 14. LED Driver



*(Increase R1 for I_L small)
 $V_L \leq V^+ - 2V$

Figure 15. Current Monitor

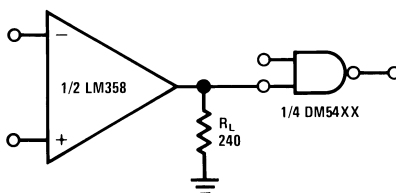
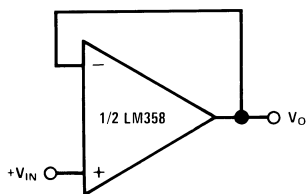


Figure 16. Driving TTL



$$V_O = V_{IN}$$

Figure 17. Voltage Follower

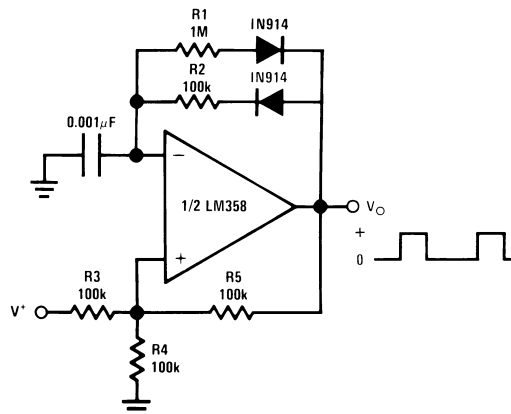


Figure 18. Pulse Generator

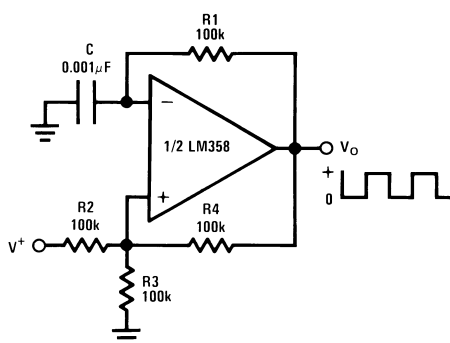


Figure 19. Squarewave Oscillator

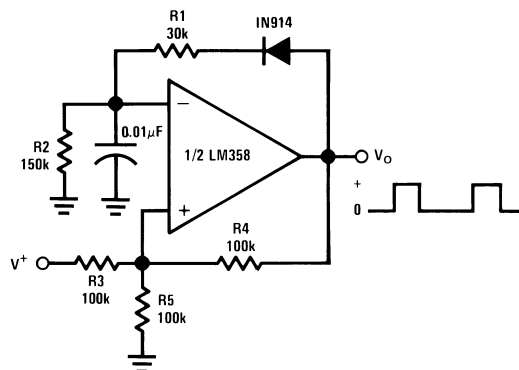


Figure 20. Pulse Generator

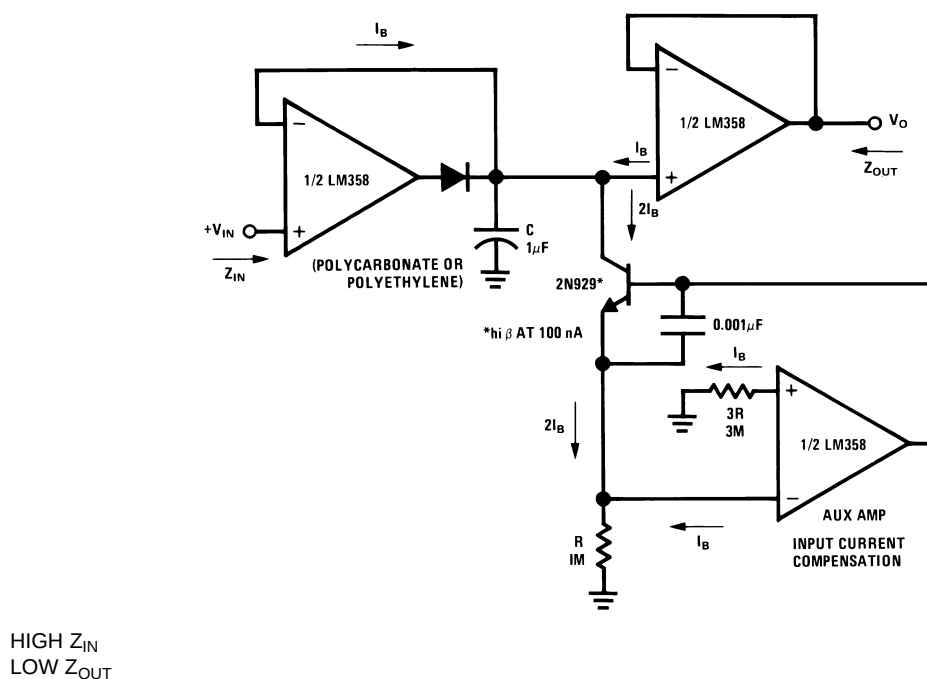
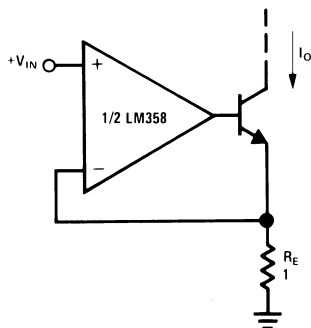


Figure 21. Low Drift Peak Detector



$I_O = 1 \text{ amp/volt } V_{IN}$
(Increase R_E for I_O small)

Figure 22. High Compliance Current Sink

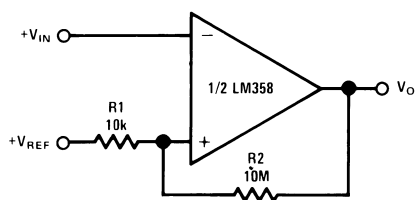
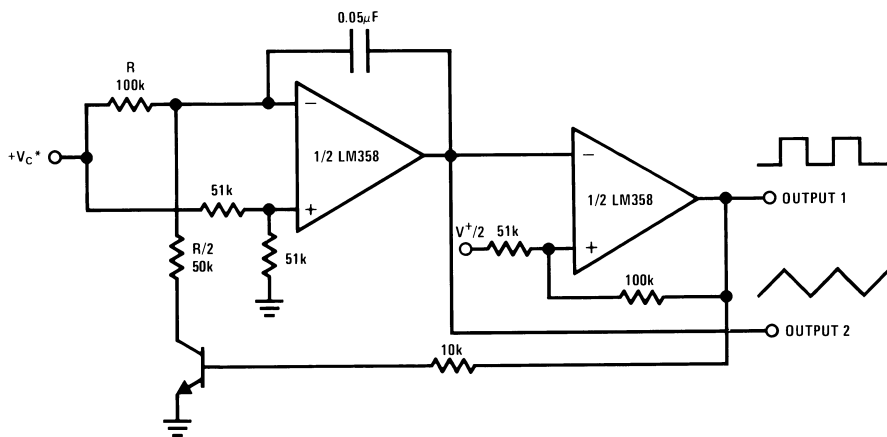


Figure 23. Comparator with Hysteresis



*WIDE CONTROL VOLTAGE RANGE: $0 V_{DC} \leq V_C \leq 2 (V^+ - 1.5V_{DC})$

Figure 24. Voltage Controlled Oscillator (VCO)

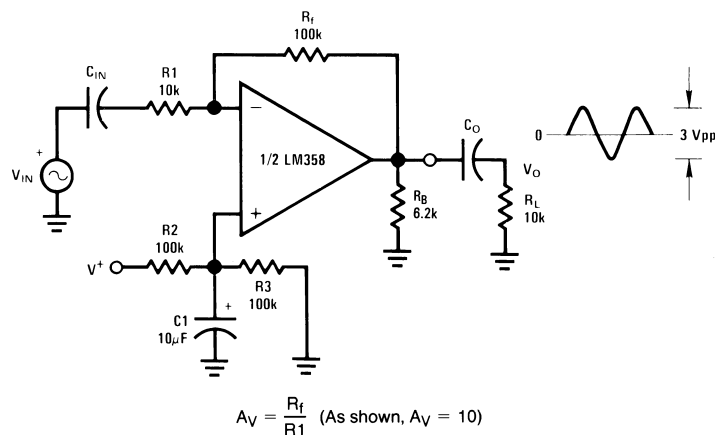


Figure 25. AC Coupled Inverting Amplifier

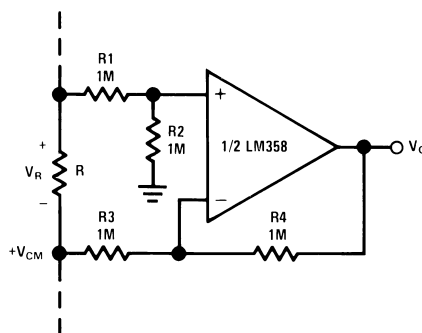
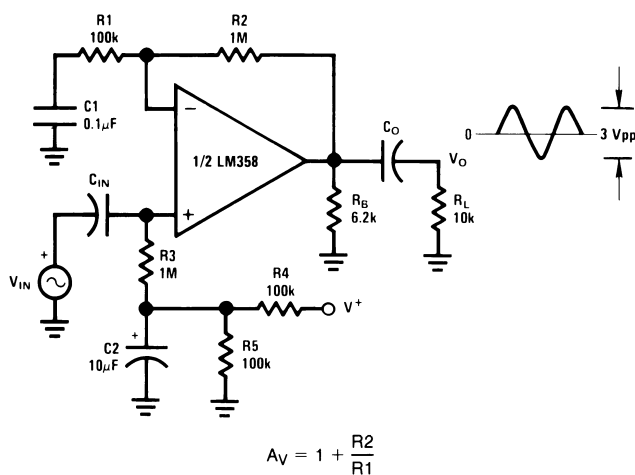
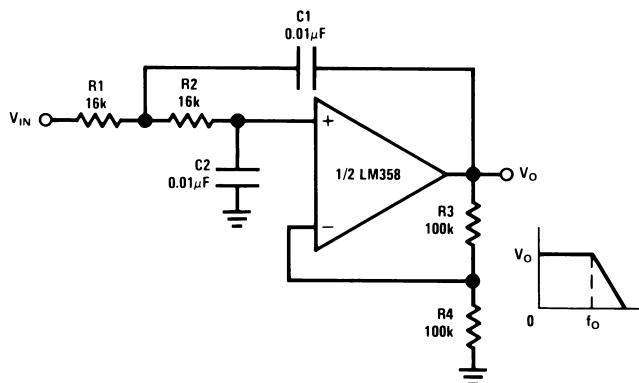


Figure 26. Ground Referencing a Differential Input Signal



$A_V = 11$ (As Shown)

Figure 27. AC Coupled Non-Inverting Amplifier

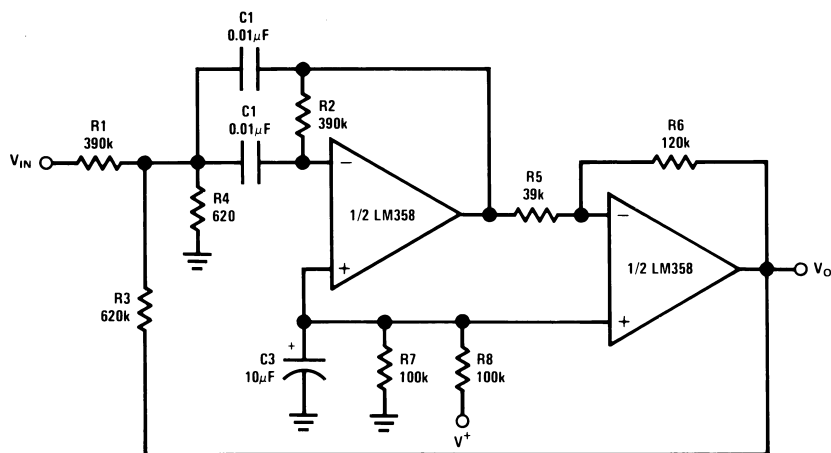


$$f_o = 1 \text{ kHz}$$

$$Q = 1$$

$$A_V = 2$$

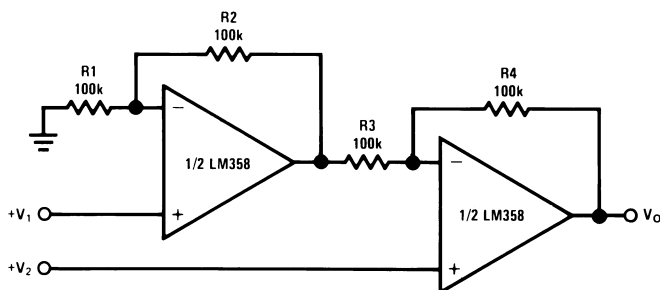
Figure 28. DC Coupled Low-Pass RC Active Filter



$$f_o = 1 \text{ kHz}$$

$$Q = 25$$

Figure 29. Bandpass Active Filter



$$\text{For } \frac{R1}{R2} = \frac{R4}{R3} \text{ (CMRR depends on this resistor ratio match)}$$

$$V_O = 1 + \frac{R4}{R3} (V_2 - V_1)$$

$$\text{As Shown: } V_O = 2 (V_2 - V_1)$$

Figure 30. High Input Z, DC Differential Amplifier

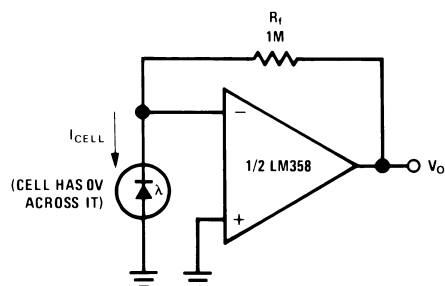
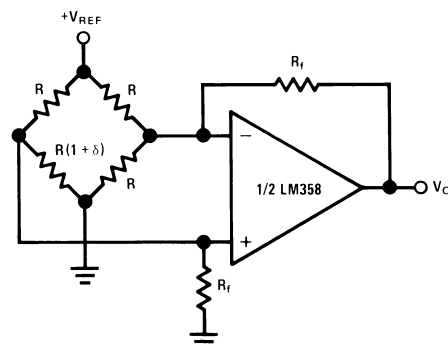


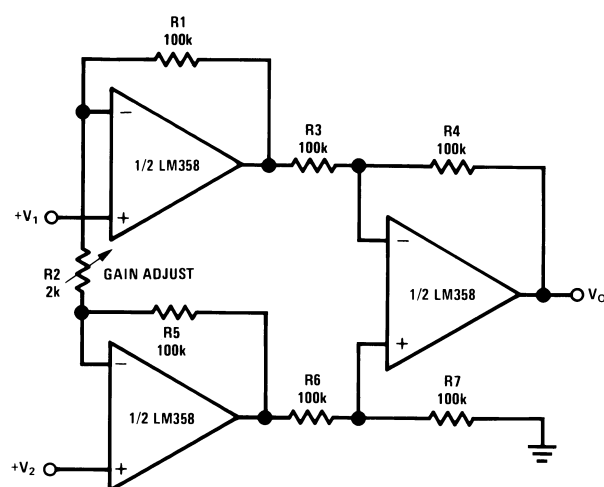
Figure 31. Photo Voltaic-Cell Amplifier



For $\delta \ll 1$ and $R_f \gg R$

$$V_O \cong V_{REF} \left(\frac{\delta}{2} \right) \frac{R_f}{R}$$

Figure 32. Bridge Current Amplifier



If $R1 = R5$ & $R3 = R4 = R6 = R7$ (CMRR depends on match)

$$V_O = 1 + \frac{2R1}{R2} (V_2 - V_1)$$

As shown $V_O = 101 (V_2 - V_1)$

Figure 33. High Input Z Adjustable-Gain DC Instrumentation Amplifier

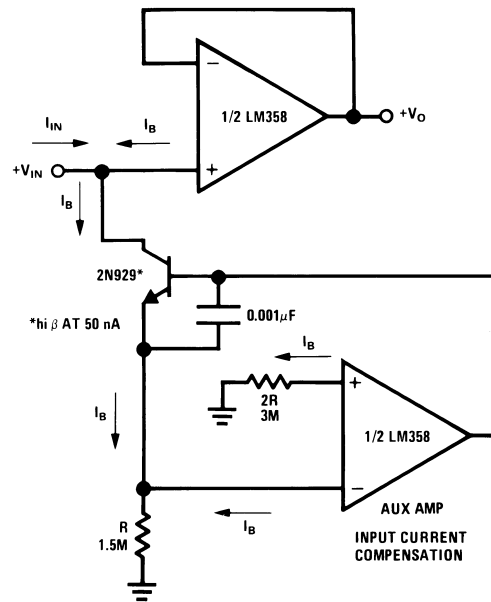
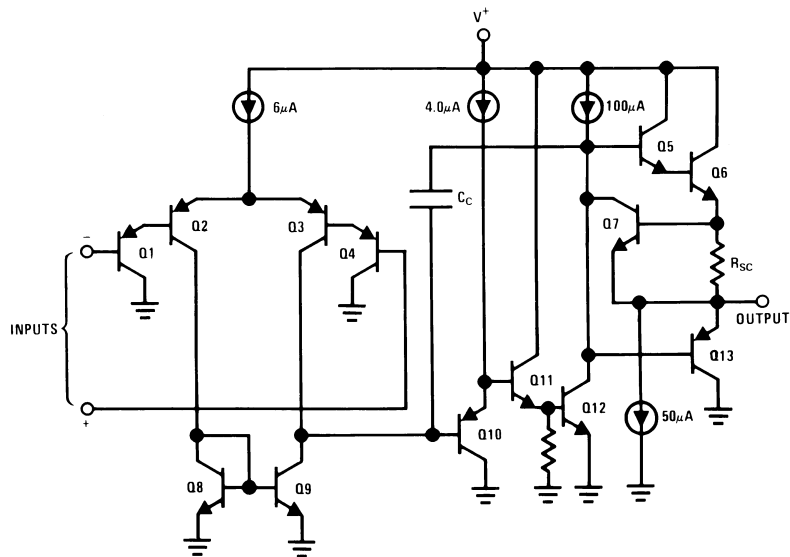


Figure 34. Using Symmetrical Amplifiers to Reduce Input Current (General Concept)

SCHEMATIC DIAGRAM

(Each Amplifier)



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM158AH	ACTIVE	TO-99	LMC	8	500	TBD	POST-PLATE	Level-1-NA-UNLIM	-55 to 125	LM158AH	Samples
LM158AH/NOPB	ACTIVE	TO-99	LMC	8	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-55 to 125	LM158AH	Samples
LM158H	ACTIVE	TO-99	LMC	8	500	TBD	POST-PLATE	Level-1-NA-UNLIM	-55 to 125	LM158H	Samples
LM158H/NOPB	ACTIVE	TO-99	LMC	8	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-55 to 125	LM158H	Samples
LM158J	ACTIVE	CDIP	NAB	8	40	TBD	A42 SNPB	Level-1-NA-UNLIM	-55 to 125	LM158J	Samples
LM258H	ACTIVE	TO-99	LMC	8	500	TBD	POST-PLATE	Level-1-NA-UNLIM	-25 to 85	LM258H	Samples
LM258H/NOPB	ACTIVE	TO-99	LMC	8	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-25 to 85	LM258H	Samples
LM2904ITP/NOPB	ACTIVE	DSBGA	YPB	8	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	A 09	Samples
LM2904ITPX/NOPB	ACTIVE	DSBGA	YPB	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	A 09	Samples
LM2904M	ACTIVE	SOIC	D	8	95	TBD	CU SNPB	Level-1-235C-UNLIM	-40 to 85	LM 2904M	Samples
LM2904M/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM 2904M	Samples
LM2904MX	ACTIVE	SOIC	D	8	2500	TBD	CU SNPB	Level-1-235C-UNLIM	-40 to 85	LM 2904M	Samples
LM2904MX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM 2904M	Samples
LM2904N	ACTIVE	PDIP	P	8	40	TBD	SNPB	Level-1-NA-UNLIM	-40 to 85	LM 2904N	Samples
LM2904N/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-40 to 85	LM 2904N	Samples
LM358AM	ACTIVE	SOIC	D	8	95	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM 358AM	Samples
LM358AM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM 358AM	Samples
LM358AMX	ACTIVE	SOIC	D	8	2500	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM 358AM	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM358AMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM 358AM	Samples
LM358AN	ACTIVE	PDIP	P	8	40	TBD	SNPB	Level-1-NA-UNLIM	0 to 70	LM 358AN	Samples
LM358AN/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	SN	Level-1-NA-UNLIM	0 to 70	LM 358AN	Samples
LM358H	ACTIVE	TO-99	LMC	8	500	TBD	POST-PLATE	Level-1-NA-UNLIM	0 to 70	LM358H	Samples
LM358H/NOPB	ACTIVE	TO-99	LMC	8	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	0 to 70	LM358H	Samples
LM358M	ACTIVE	SOIC	D	8	95	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM 358M	Samples
LM358M/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM 358M	Samples
LM358MX	ACTIVE	SOIC	D	8	2500	TBD	CU SNPB	Level-1-235C-UNLIM	0 to 70	LM 358M	Samples
LM358MX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM 358M	Samples
LM358N	ACTIVE	PDIP	P	8	40	TBD	Call TI	Level-1-NA-UNLIM	0 to 70	LM 358N	Samples
LM358N/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	0 to 70	LM 358N	Samples
LM358TP/NOPB	ACTIVE	DSBGA	YPB	8	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	0 to 70	A 07	Samples
LM358TPX/NOPB	ACTIVE	DSBGA	YPB	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	0 to 70	A 07	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

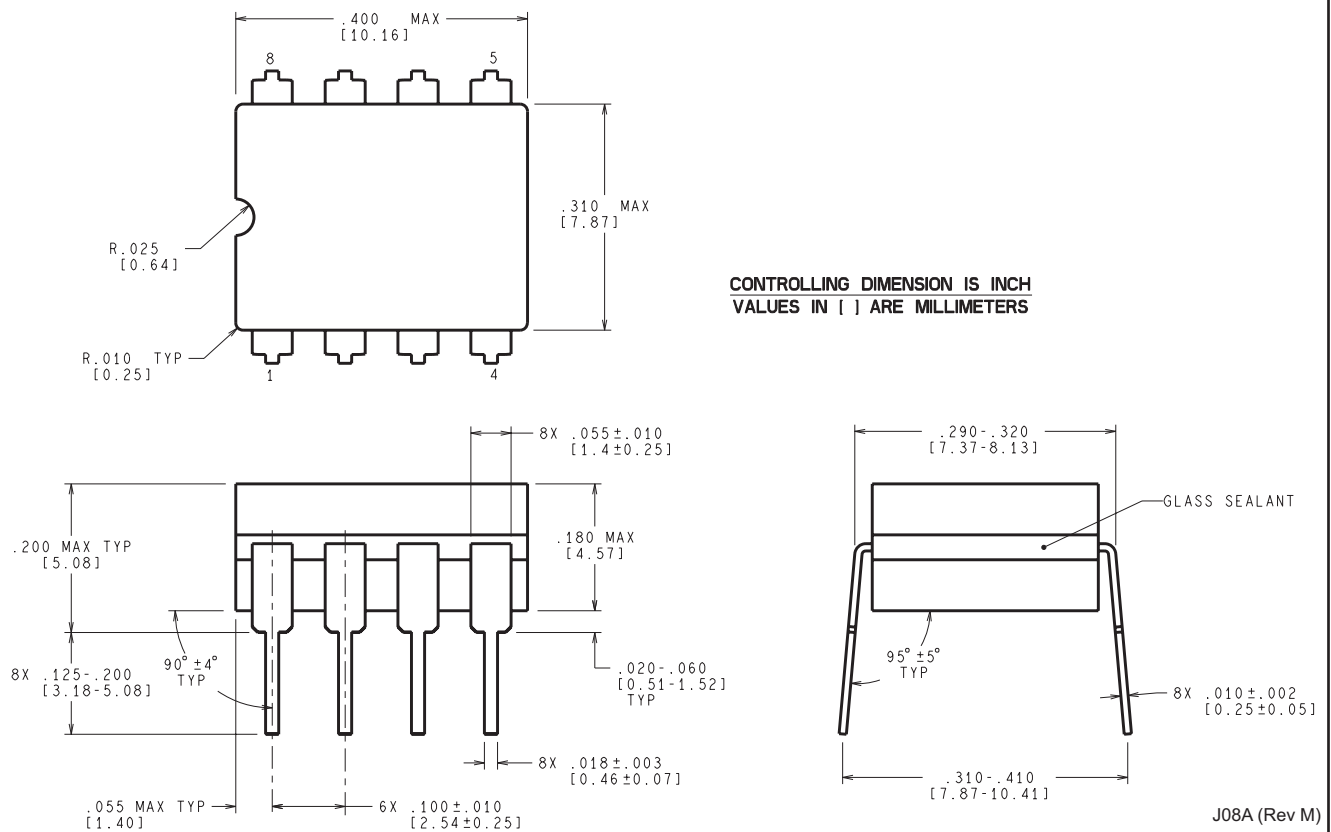
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2904ITP/NOPB	DSBGA	YPB	8	250	178.0	8.4	1.5	1.5	0.66	4.0	8.0	Q1
LM2904ITPX/NOPB	DSBGA	YPB	8	3000	178.0	8.4	1.5	1.5	0.66	4.0	8.0	Q1
LM2904MX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM2904MX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM358AMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM358AMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM358MX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM358MX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM358TP/NOPB	DSBGA	YPB	8	250	178.0	8.4	1.5	1.5	0.66	4.0	8.0	Q1
LM358TPX/NOPB	DSBGA	YPB	8	3000	178.0	8.4	1.5	1.5	0.66	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



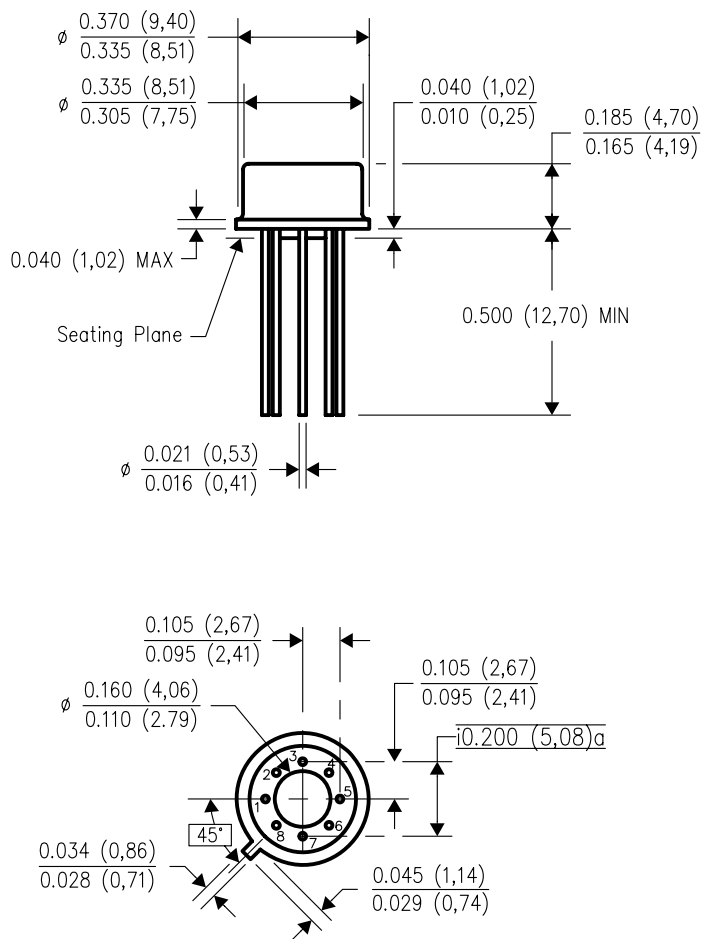
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2904ITP/NOPB	DSBGA	YPB	8	250	203.0	190.0	41.0
LM2904ITPX/NOPB	DSBGA	YPB	8	3000	206.0	191.0	90.0
LM2904MX	SOIC	D	8	2500	349.0	337.0	45.0
LM2904MX/NOPB	SOIC	D	8	2500	349.0	337.0	45.0
LM358AMX	SOIC	D	8	2500	349.0	337.0	45.0
LM358AMX/NOPB	SOIC	D	8	2500	349.0	337.0	45.0
LM358MX	SOIC	D	8	2500	349.0	337.0	45.0
LM358MX/NOPB	SOIC	D	8	2500	349.0	337.0	45.0
LM358TP/NOPB	DSBGA	YPB	8	250	203.0	190.0	41.0
LM358TPX/NOPB	DSBGA	YPB	8	3000	206.0	191.0	90.0



LMC (O-MBCY-W8)

METAL CYLINDRICAL PACKAGE



4202483/B 09/07

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Leads in true position within 0.010 (0,25) R @ MMC at seating plane.
 - Pin numbers shown for reference only. Numbers may not be marked on package.
 - Falls within JEDEC MO-002/TO-99.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.



E: Max = 1.357 mm, Min =1.256 mm

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.

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